



US 20240213077A1

(19) **United States**(12) **Patent Application Publication**
LEE et al.(10) **Pub. No.: US 2024/0213077 A1**(43) **Pub. Date: Jun. 27, 2024**(54) **SUBSTRATE PROCESSING APPARATUS**(52) **U.S. Cl.**(71) Applicant: **SEMES CO, LTD.**, Cheonan-si (KR)CPC .. **H01L 21/68742** (2013.01); **H01L 21/67051**
(2013.01); **H01L 21/68764** (2013.01); **H05F**
3/04 (2013.01)(72) Inventors: **Jeongcheol LEE**, Incheon-si (KR);
Jungheum NAM, Gyeongju-si (KR);
Kyungmo KIM, Asan-si (KR); **Woojin**
CHUNG, Seongnam-si (KR);
Myunggeun MIN, Cheonan-si (KR)

(57)

ABSTRACT(73) Assignee: **SEMES CO, LTD.**, Cheonan-si (KR)(21) Appl. No.: **18/069,478**(22) Filed: **Dec. 21, 2022**(30) **Foreign Application Priority Data**

Dec. 31, 2021 (KR) 10-2021-0194466

Publication Classification(51) **Int. Cl.****H01L 21/687** (2006.01)**H01L 21/67** (2006.01)**H05F 3/04** (2006.01)

There is provided a substrate processing apparatus. The substrate processing apparatus may include a substrate supporter supporting a substrate, a processing solution feeder supplying a processing solution to the substrate, first and second recovery containers configured to recover the processing solution, a first pipe connected to the first recovery container and including an insulating material, a second pipe connected to the second recovery container and including an insulating material, a first static electricity eliminator in contact with the first pipe, a second static electricity eliminator in contact with the second pipe, and a plurality of first conductive lines connected to the first and second static electricity eliminators.

